

REMARKS/ARGUMENTS

Claims 26, 27 and 34-38 have been examined. Claims 28-33 have been withdrawn as being directed to nonelected subject matter. Claims 26 and 27 have been amended for clarity. Accordingly, the Applicants do not believe that any new matter has been introduced. Favorable consideration and allowance of the application is now respectfully requested.

Election/Restriction

The Elected Species II is directed to an electronic device having a condensable fluid as shown in Figure 4. The election/restriction requirement has now been made FINAL.

The Applicants traverse the withdrawal of Claims 28-33 on the grounds that they are directed to nonelected subject matter. These claims depend from Claim 26 which claims the elected Species II which comprises an electronic device having a condensable fluid as shown in Fig. 4. Accordingly, the Applicants respectfully request formal rejoinder of these claims.

Rejection-35 U.S.C. § 112, Second Paragraph

Claims 26, 27 and 34-38 were rejected under 35 U.S.C. § 112, second paragraph, as being indefinite. These rejections are moot in view of the amendments above.

Rejections - 35 U.S.C. § 102(b) and 103(a)

Claim 26, 27 and 34 were rejected under 35 U.S.C. § 102(b) as being anticipated by U.S. Patent No. 6,317,322 to Ueki et al and Claims 35-38 were rejected under 35 U.S.C. §103(a) as being unpatentable over the same reference. The Applicants traverse these rejections since Ueki does not disclose or suggest an electronic device comprising “means for joining the die or electronic part to the heat spreader so that thermal stress that causes

separation of the die or electronic part and the heat spreader does not occur” as required by Claim 26.

The present invention overcomes the problem of electronic component separation caused by thermal stress as described in the specification on page 2, lines 19-24. The present invention overcomes this problem by joining the electronic part (or die) and heat spreader (page 2, lines 25-26) in a way that minimizes thermal stress so that the separation of the electronic parts does not occur.

On the other hand, the parts of the device disclosed by Fig. 9 of Ueki are not joined at all. According, to col. 2, lines 54-*et seq.* these parts are merely contacted and heat transfer grease is applied between them. Ueki discloses the need to have “highly preciseness in size” (line 55) and “flatness of the contact surface” (lines 61-62) to accomplish this objective. Thus, Ueki does not disclose all the elements of the present invention, specifically the requirement for joining the electronic part and the heat spreader, and cannot provide a reasonable expectation of success for the present invention which joins these elements in a way to minimize thermal stress and prevent their separation.

The Applicants submit that Ueki does not disclose or suggest joining the electronic part and heat spreader and provides no suggestion at all to select an electronic part (or die) component and a heat spreader component that have about the same coefficients of thermal expansion such that they do not generate significant thermal stress. The Official Action (page 4) indicates that the die or electronic part (52) and the heat spreader components (50) are selected to have about the same coefficients of thermal expansion. However, a key word search of Ueki shows that the words “coefficient” and “separation” do not appear in the patent. While col. 2, lines 26-30, indicates it is important to contact the cooling pipe 7 with the heat generating part 52 which is to be cooled in least heat resistance, the device of Fig. 9 as described by Ueki does this by carefully controlling the geometry of the parts (as described

in more detail in col. 2, lines 32-*et seq.*) and not by joining parts having the same coefficients of thermal expansion. Accordingly, the Applicants respectfully request that these rejections now be withdrawn.

CONCLUSION

In view of the above amendments and remarks the Applicants respectfully submit that this application is now in condition for allowance. Early notification to that effect is respectfully requested.

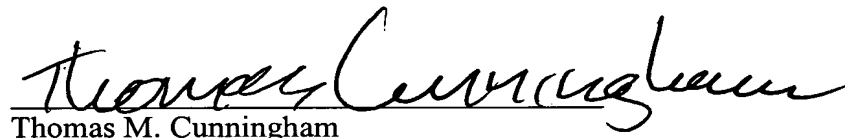
Respectfully submitted,

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